

# XC7WT14

## Triple inverting Schmitt trigger

Rev. 3 — 23 January 2013

Product data sheet

### 1. General description

The XC7WT14 is a high-speed Si-gate CMOS device. This device provides three inverting buffers with Schmitt trigger action. This device is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

### 2. Features and benefits

- Symmetrical output impedance
- High noise immunity
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM JESD22-C101D exceeds 1000 V
- Low power dissipation
- Balanced propagation delays
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Applications

- Wave and pulse shaper for highly noisy environment
- Astable multivibrator
- Monostable multivibrator

### 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
XC7WT14DP	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	TSSOP8	plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm	SOT505-2
XC7WT14DC	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm	SOT765-1
XC7WT14GT	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body $1 \times 1.95 \times 0.5\text{ mm}$	SOT833-1
XC7WT14GD	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body $3 \times 2 \times 0.5\text{ mm}$	SOT996-2



5. Marking

Table 2. Marking codes

Type number	Marking code <sup>[1]</sup>
XC7WT14DP	g14
XC7WT14DC	g14
XC7WT14GT	g14
XC7WT14GD	g14

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

6. Functional diagram

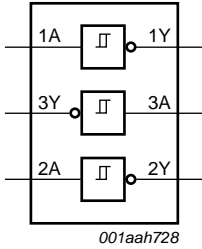


Fig 1. Logic symbol

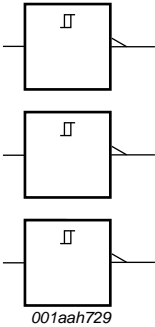


Fig 2. IEC logic symbol

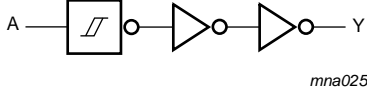


Fig 3. Logic diagram (one Schmitt trigger)

7. Pinning information

7.1 Pinning

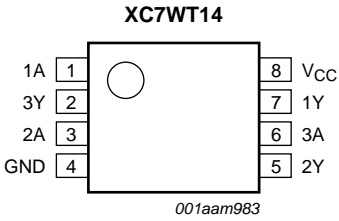


Fig 4. Pin configuration SOT505-2 and SOT765-1

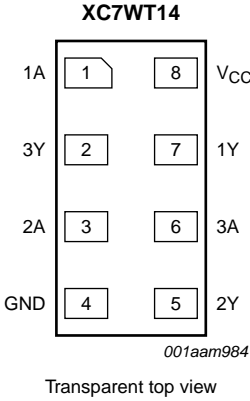
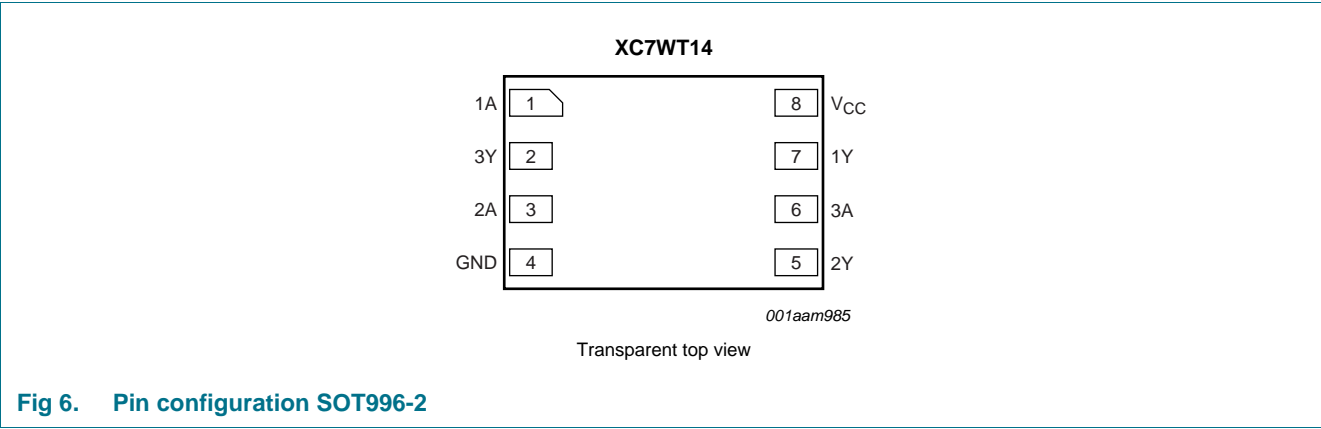


Fig 5. Pin configuration SOT833-1



7.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
1A, 2A, 3A	1, 3, 6	data input
GND	4	ground (0 V)
1Y, 2Y, 3Y	7, 5, 2	data output
V <sub>CC</sub>	8	supply voltage

8. Functional description

Table 4. Function table [\[1\]](#)

Input nA	Output nY
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level

## 9. Limiting values

**Table 5. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		-0.5	+7.0	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V	-20	-	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1] -	±20	mA
$I_O$	output current	$-0.5$ V < $V_O$ < $V_{CC} + 0.5$ V	-	±25	mA
$I_{CC}$	supply current		-	75	mA
$I_{GND}$	ground current		-75	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For TSSOP8 package: above 55 °C the value of  $P_{tot}$  derates linearly at 2.5 mW/K.

For VSSOP8 package: above 110 °C the value of  $P_{tot}$  derates linearly at 8 mW/K.

For XSON8 packages: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 10. Recommended operating conditions

**Table 6. Recommended operating conditions**

*Voltages are referenced to GND (ground = 0 V).*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C

## 11. Static characteristics

**Table 7. Static characteristics**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T–</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = –50 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = –8.0 mA	3.94	-	-	3.8	-	3.70	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>T+</sub> or V <sub>T–</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 50 µA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	1.0	-	10	-	40	µA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = 3.4 V; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C <sub>I</sub>	input capacitance		-	1.5	10	-	10	-	10	pF

## 11.1 Transfer characteristics

**Table 8. Transfer characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V). See [Figure 9](#) and [Figure 10](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>T+</sub>	positive-going threshold voltage	V <sub>CC</sub> = 4.5 V	-	-	2.0	-	2.0	-	2.0	V
		V <sub>CC</sub> = 5.5 V	-	-	2.0	-	2.0	-	2.0	V
V <sub>T–</sub>	negative-going threshold voltage	V <sub>CC</sub> = 4.5 V	0.5	-	-	0.5	-	0.5	-	V
		V <sub>CC</sub> = 5.5 V	0.6	-	-	0.6	-	0.6	-	V
V <sub>H</sub>	hysteresis voltage	V <sub>CC</sub> = 4.5 V	0.4	-	1.4	0.4	1.4	0.35	1.4	V
		V <sub>CC</sub> = 5.5 V	0.4	-	1.6	0.4	1.6	0.35	1.6	V

## 12. Dynamic characteristics

**Table 9. Dynamic characteristics**

GND = 0 V; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t <sub>pd</sub>	propagation delay	nA to nY; <a href="#">Figure 7</a> <a href="#">[1]</a> <a href="#">[2]</a>								
		C <sub>L</sub> = 15 pF	-	4.1	7.0	1.0	8.0	1.0	9.0	ns
		C <sub>L</sub> = 50 pF	-	5.9	8.5	1.0	10.0	1.0	11.0	ns
C <sub>PD</sub>	power dissipation capacitance	per buffer; <a href="#">[3]</a> V <sub>I</sub> = GND to V <sub>CC</sub>	-	12	-	-	-	-	-	pF

[1] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[2] Typical values are measured at V<sub>CC</sub> = 5.0 V.

[3] C<sub>PD</sub> is used to determine the dynamic power dissipation P<sub>D</sub> (μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where:

f<sub>i</sub> = input frequency in MHz;

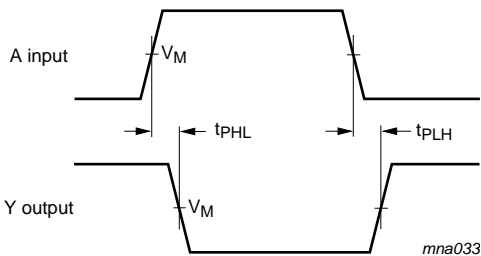
f<sub>o</sub> = output frequency in MHz;

C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

Σ(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.

13. Waveforms

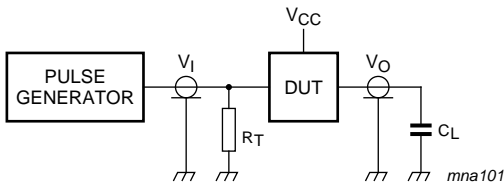


Measurement points are given in [Table 10](#).

Fig 7. The input (nA) to output (nY) propagation delays

Table 10. Measurement points

Type number	Input		Output
	$V_I$	$V_M$	$V_M$
XC7WT14	GND to 3.0 V	1.5 V	$0.5 \times V_{CC}$



Test data is given in [Table 11](#).

Definitions for test circuit:

$C_L$  = Load capacitance including jig and probe capacitance.

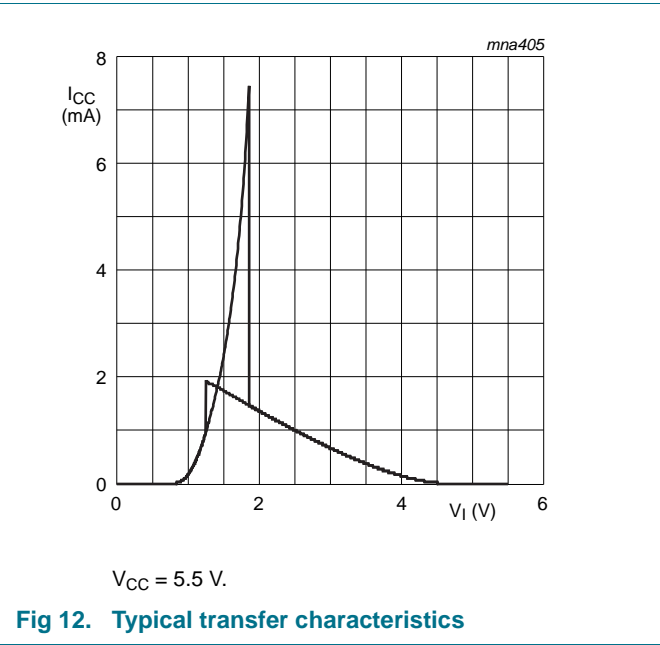
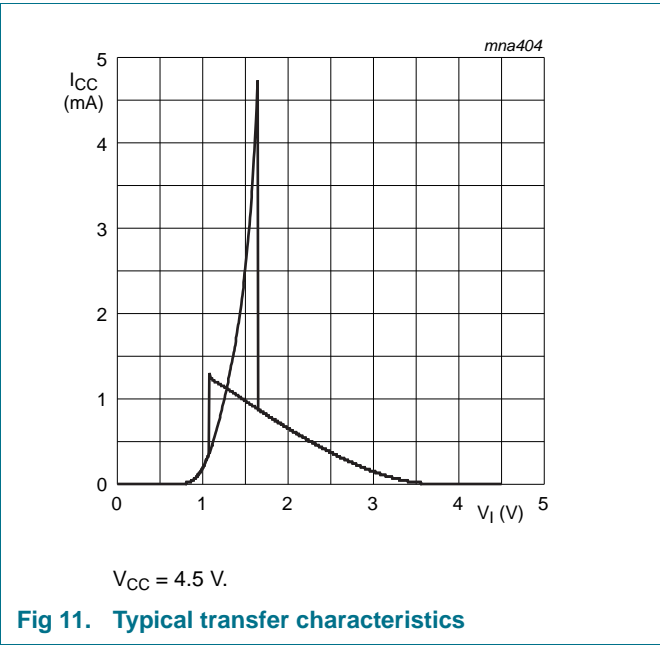
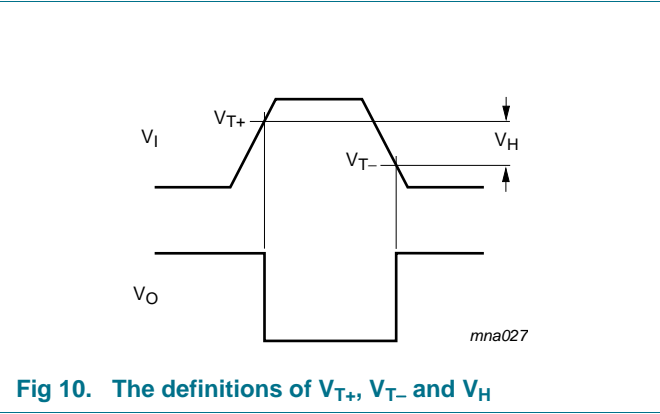
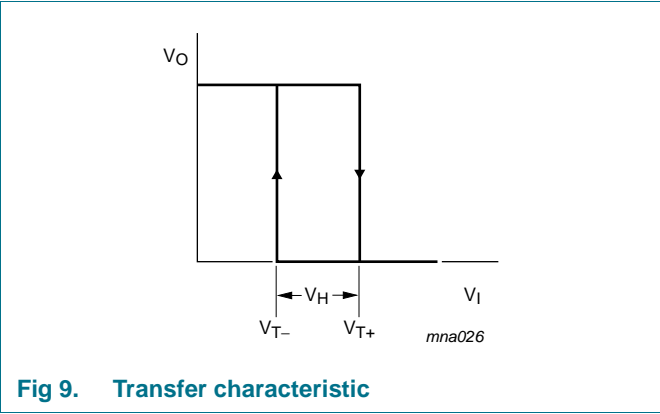
$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

Fig 8. Test circuit for measuring switching times

Table 11. Test data

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
XC7WT14	3.0 V	$\leq 3.0$ ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

13.1 Transfer characteristic waveforms





## 14. Application information

The slow input rise and fall times cause additional power dissipation, which can be calculated using the following formula:

$$P_{\text{add}} = f_i \times (t_r \times \Delta I_{\text{CC(AV)}} + t_f \times \Delta I_{\text{CC(AV)}}) \times V_{\text{CC}} \text{ where:}$$

$P_{\text{add}}$  = additional power dissipation ( $\mu\text{W}$ );

$f_i$  = input frequency (MHz);

$t_r$  = input rise time (ns); 10 % to 90 %;

$t_f$  = input fall time (ns); 90 % to 10 %;

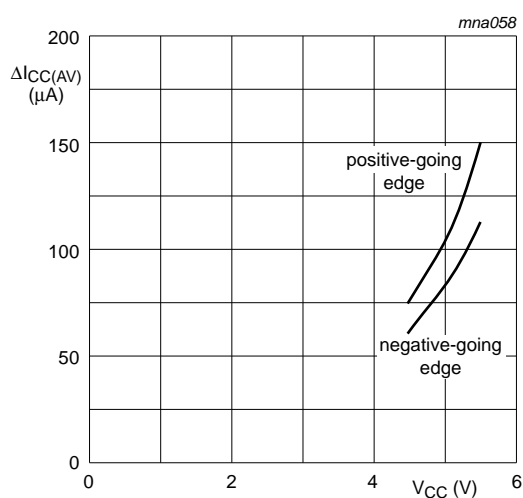
$\Delta I_{\text{CC(AV)}}$  = average additional supply current ( $\mu\text{A}$ ).

$\Delta I_{\text{CC(AV)}}$  differs with positive or negative input transitions, as shown in [Figure 13](#).

For XC7WT14 used in relaxation oscillator circuit, see [Figure 14](#).

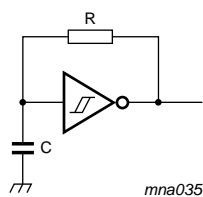
### Note to the application information:

1. All values given are typical unless otherwise specified.



Linear change of  $V_I$  between  $0.1V_{\text{CC}}$  to  $0.9V_{\text{CC}}$

**Fig 13. Average additional  $I_{\text{CC}}$**



$$f = \frac{1}{T} \approx \frac{1}{0.60 \times RC}$$

Fig 14. Relaxation oscillator using the XC7WT14

15. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm    SOT505-2

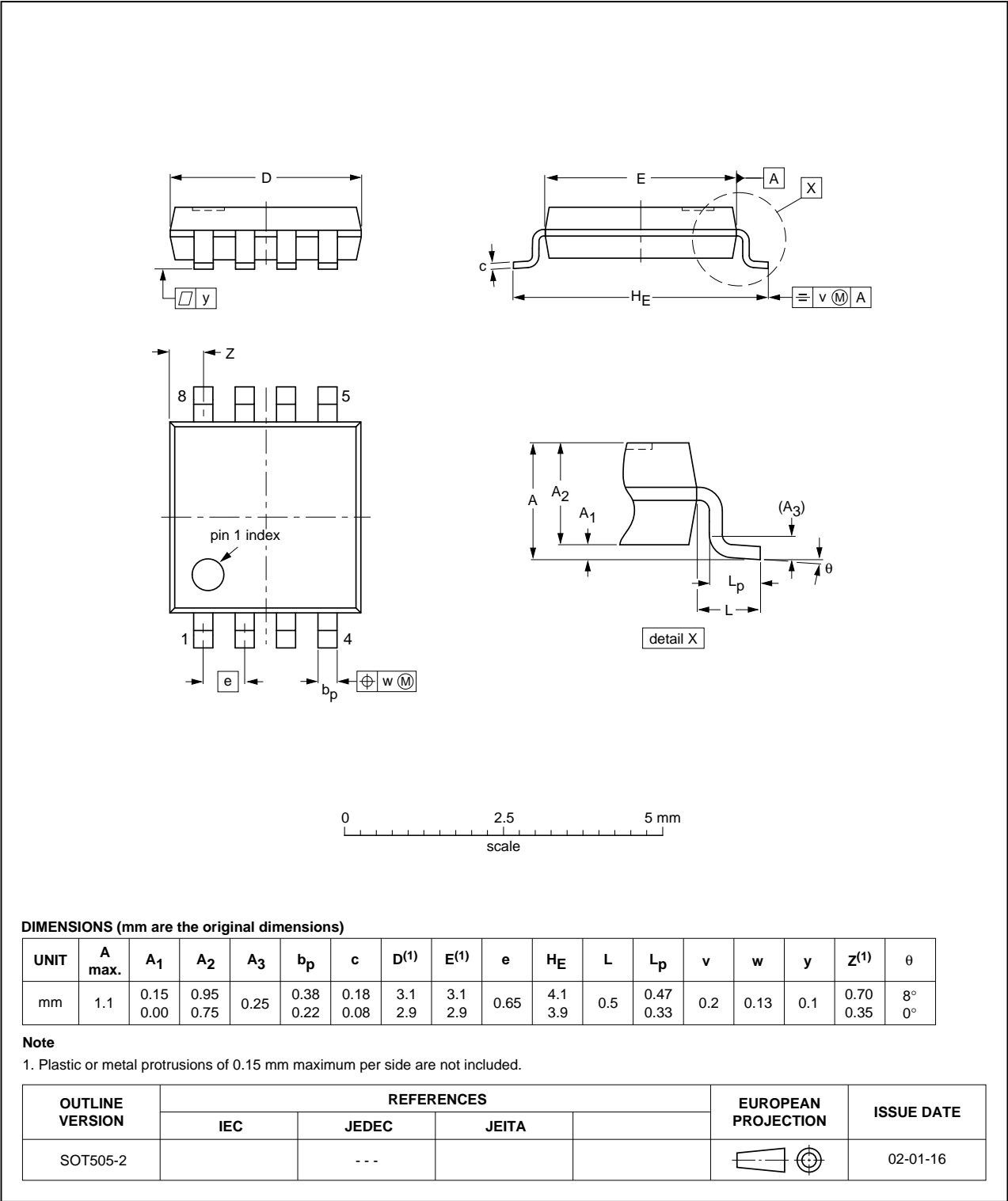


Fig 15. Package outline SOT505-2 (TSSOP8)

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1

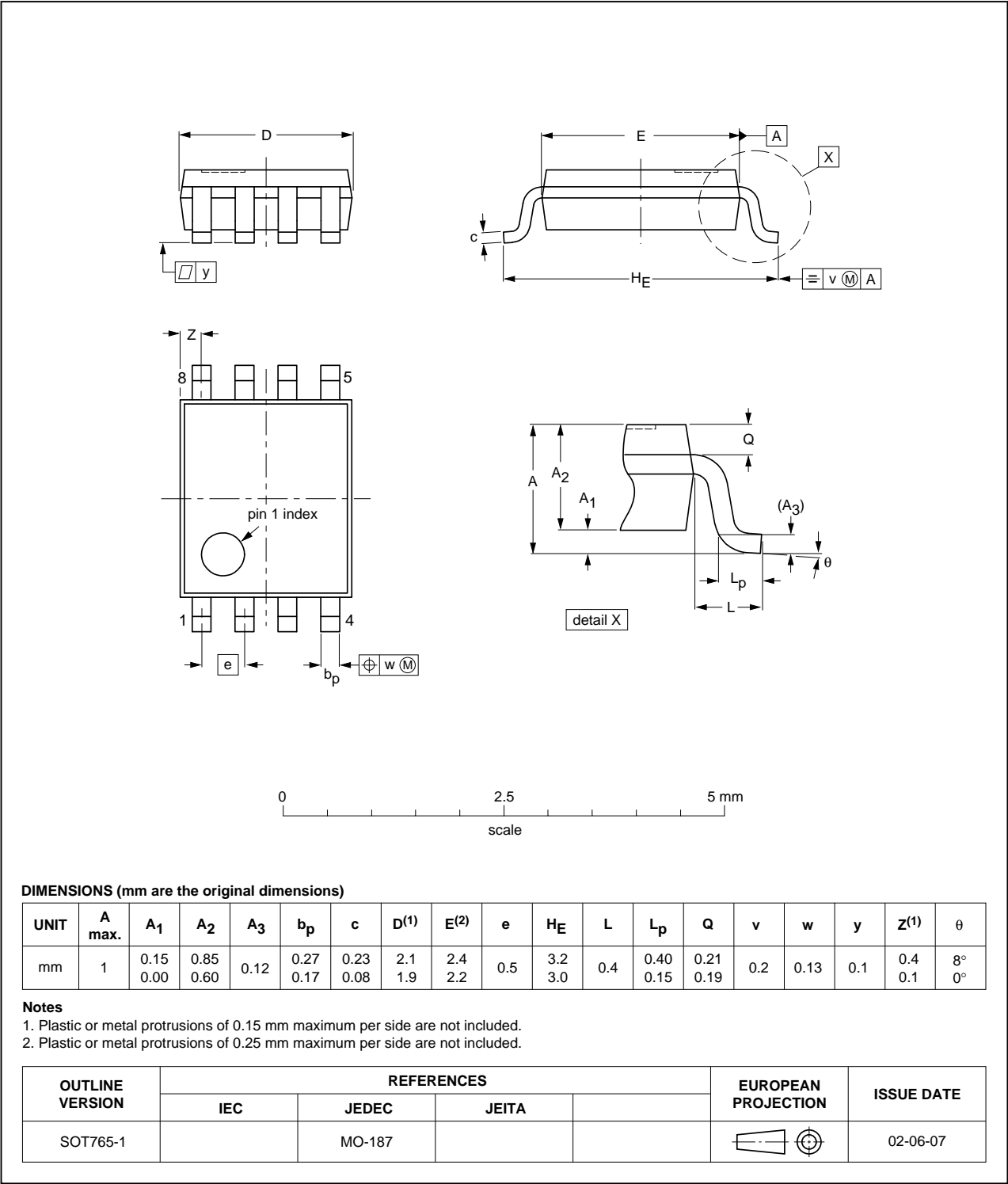


Fig 16. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads; 8 terminals; body 1 x 1.95 x 0.5 mm

SOT833-1

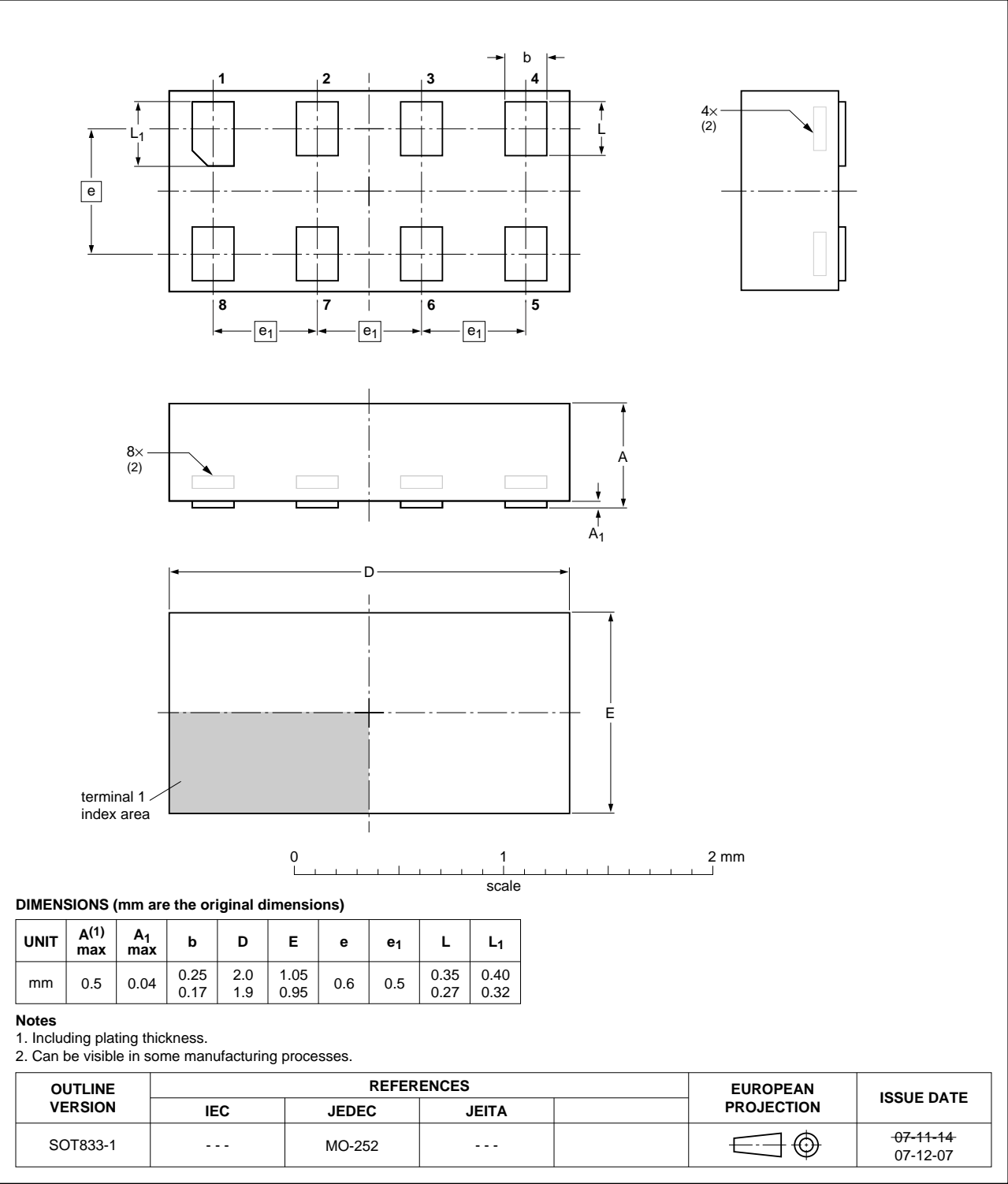


Fig 17. Package outline SOT833-1 (XSON8)

XSON8: plastic extremely thin small outline package; no leads;  
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

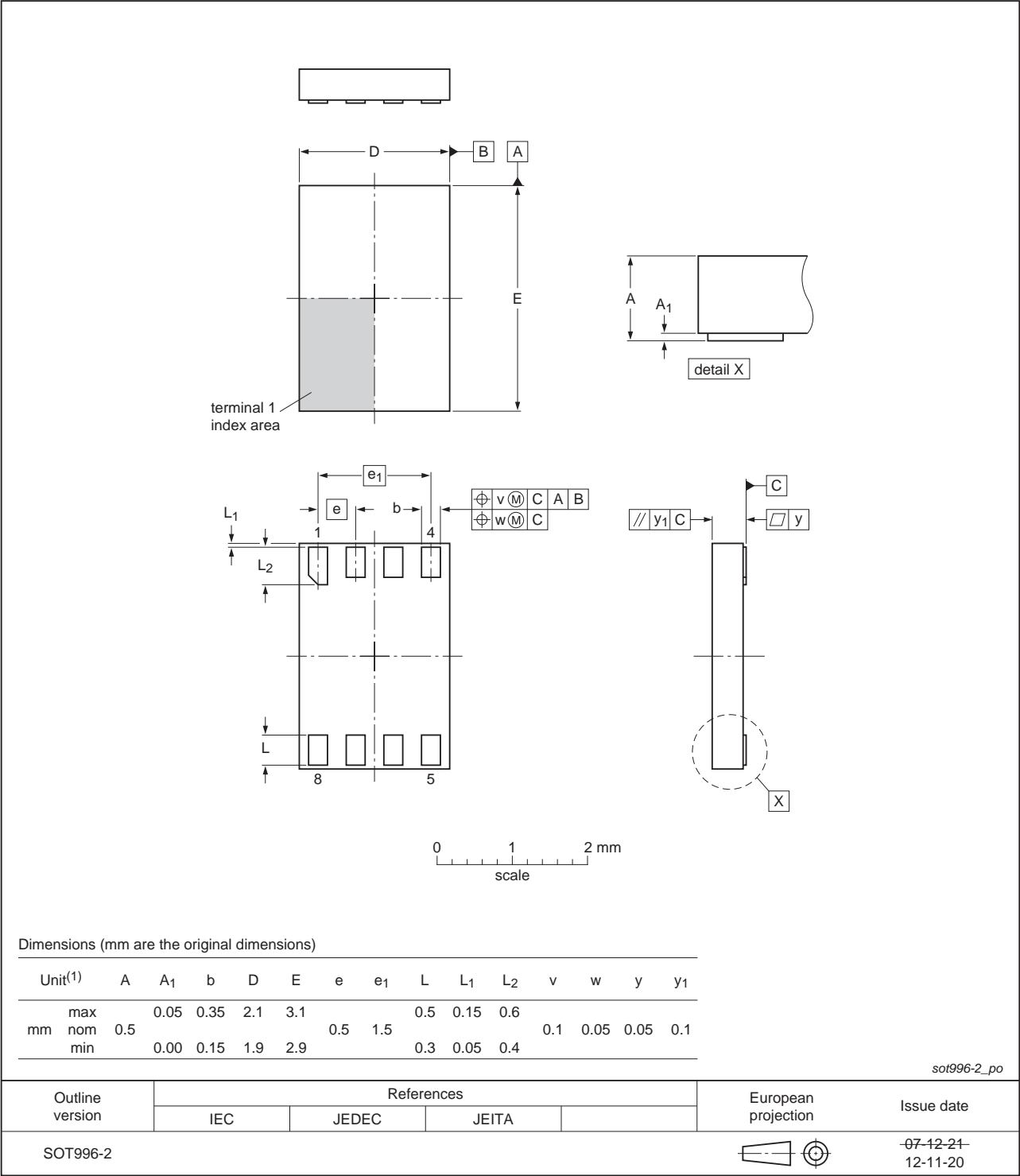


Fig 18. Package outline SOT996-2 (XSON8)

## 16. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 17. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
XC7WT14 v.3	20130123	Product data sheet	-	XC7WT14 v.2
Modifications:	• For type number XC7WT14GD XSON8U has changed to XSON8.			
XC7WT14 v.2	20111103	Product data sheet	-	XC7WT14 v.1
XC7WT14 v.1	20110119	Product data sheet	-	-

## 18. Legal information

### 18.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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